PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company	STMicroelectronics International N.V
1.2 PCN No.	EMBEDDED PROCESSING/25/15360
1.3 Title of PCN	STM32MP23x & STM32MP25x - Product enhancement
1.4 Product Category	STM32MP257x STM32MP255x STM32MP253x STM32MP251x STM32MP235x STM32MP233x STM32MP231x
1.5 Issue date	2025-09-16

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	PIKE EMMA
2.1.2 Phone	+44 1628896111
2.1.3 Email	emma.pike@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Patrick AIDOUNE
2.1.2 Marketing Manager	Veronique BARLATIER
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	**3.2 Type of change**	**3.3 Manufacturing Location**
General Product & Design	Die redesign : Mask or mask set change with new die design like metallization (specifically chip frontside) or bug fix	TSMC FAB14 (Taiwan)

4. Description of change

	Old	**New**
4.1 Description	Current STM32MP23x and STM32MP25x (Die 505 - cut2.1 -Revision Y) product has limitations described in Errata Sheet ES0598 - Rev 4 - April 2025	New STM32MP23x and STM32MP25x (Die 505 - cut2.2 - Revision X) product enhancement fixes some limitations: - ETH1 RMII timing violation solved - ROM code: Standby modes support in Secured_Locked state - ROM code: illegal access error correction during DStandby exit in M33-TD mode - VBAT TAMPER architecture robustness improvement to avoid disturbing LSE in case of negative current injection on VSW. Details are described in Errata Sheet ES0598 - Rev 5 - August 2025
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Functionality enhancement	

5. Reason / motivation for change

5.1 Motivation	Improvements implemented to increase robustness, performances and quality of our products.
5.2 Customer Benefit	SERVICE CONTINUITY

6. Marking of parts / traceability of change

6.1 Description	Traceability ensured by ST internal tools. Die revision changes from "Y" to "X" on Package Marking

7. Timing / schedule

7.1 Date of qualification results	2025-10-30

7.2 Intended start of delivery	2025-09-30
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation			
8.1 Description	15360 MDG-GPAM RER2018 - PCN15360 STM32MP23x STM32MP25x - Die 505_X cut2.2 - Rel plan.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	**Issue Date**	2025-09-16

9. Attachments (additional documentations)
15360 Public product.pdf 15360 MDG-GPAM RER2018 - PCN15360 STM32MP23x STM32MP25x - Die 505_X cut2.2 - Rel plan.pdf 15360 _Additional information.pdf

10. Affected parts		
10. 1 Current		**10.2 New (if applicable)**
10.1.1 Customer Part No	**10.1.2 Supplier Part No**	**10.1.2 Supplier Part No**
	STM32MP231AAK3	
	STM32MP231AAL3	
	STM32MP231CAK3	
	STM32MP231CAL3	
	STM32MP231DAK3	
	STM32MP231DAL3	
	STM32MP231FAK3	
	STM32MP231FAL3	
	STM32MP233AAK3	
	STM32MP233AAL3	
	STM32MP233CAK3	
	STM32MP233CAL3	
	STM32MP233DAK3	
	STM32MP233DAL3	
	STM32MP233FAK3	
	STM32MP233FAL3	
	STM32MP235AAK3	
	STM32MP235AAL3	
	STM32MP235CAK3	
	STM32MP235CAL3	
	STM32MP235DAK3	
	STM32MP235DAL3	
	STM32MP235FAK3	
	STM32MP235FAL3	
	STM32MP257DAI3	
	STM32MP257DAK3	
	STM32MP257DAL3	
	STM32MP257FAI3	
	STM32MP257FAK3	
	STM32MP257FAL3	

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